



*[Handwritten signature]*

IBMF100407000

PATENT

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

INVENTOR: Edmund D. Blackshear ) EXAMINER: WILLIAMS, ALEXANDER O.  
SERIAL NO.: 10/719,334 ) ART UNIT: 2826  
FILING DATE: November 21, 2003 ) DATE: June 30, 2005  
FOR: Overlap Stacking of Center Bus Bonded Memory Chips for Double  
Density and Method of Manufacturing the Same

**STATUS INQUIRY REQUEST**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Applicant respectfully inquires about the status of the subject application. To date, no office action has been received since the filing of the application on November 21, 2003. Upon checking the June 28, 2005, Volume 1295 Number 4 of the Electronic Official Gazette for Patents, we find that the average filing date of applications receiving a first office action in the last three months is January 21, 2004.

A duplicate copy of this request is enclosed.

Respectfully submitted,

*[Handwritten signature of Robert Curcio]*  
Robert Curcio  
Reg. No. 44,638

**DeLIO & PETERSON, LLC**  
121 Whitney Avenue  
New Haven, CT 06510-1241  
(203) 787-0595

**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service on the date indicated below as first class mail in an envelope addressed to the Assistant Commissioner of Patents and Trademarks, Washington, D.C. 20231.

Name: Brenda Sullivan Date: 6/30/05

Signature: *[Handwritten signature of Brenda Sullivan]*